



#### DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)max</sub>	Ι <sub>D</sub> T <sub>A</sub> = +25°C
20V	15.5mΩ @ V <sub>GS</sub> = 4.5V	7.5A
	16.5mΩ @ V <sub>GS</sub> = 4.0V	7.3A
	19mΩ @ V <sub>GS</sub> = 3.1V	6.9A
	20mΩ @ V <sub>GS</sub> = 2.5V	6.7A
	30mΩ @ V <sub>GS</sub> = 1.8V	5.4A

#### Description

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(ON)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

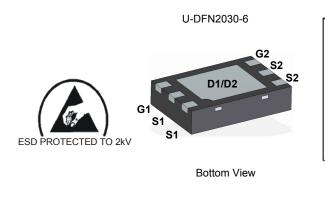
- Power Management Functions
- Battery Pack
- Load Switch

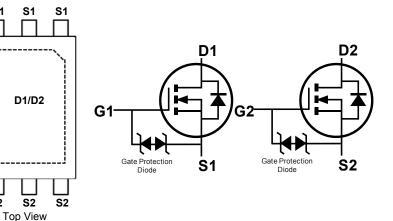
#### Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### Mechanical Data

- Case: U-DFN2030-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.012 grams (approximate)





# Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2016LHAB-7	U-DFN2030-6	3,000 / Tape & Reel

Pin Configuration

Bottom Drain Contact

G1

G2

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

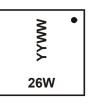
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

## **Marking Information**

Notes:



26W = Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 12 for 2012) WW = Week code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Character	Symbol	Value	Unit		
Drain-Source Voltage	V <sub>DSS</sub>	20	V		
Gate-Source Voltage	V <sub>GSS</sub>	±12	V		
	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	ID	7.5 5.8	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t < 10s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	7.7 6.0	А
Pulsed Drain Current (10µs pulse, duty cycle = 1	IDM	45	A		

## **Thermal Characteristics**

Characteristic	Symbol	Value	Units		
Total Dower Dissingtion (Nate 5)	T <sub>A</sub> = +25°C	D	1.2	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.75		
Thermal Desistance Junction to Ambient (Note E)	Steady State	D	106	°C/W	
Thermal Resistance, Junction to Ambient (Note 5)	t < 10s	R <sub>θJA</sub>	100	C/W	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	D	1.65	W	
	T <sub>A</sub> = +70°C	PD	1	vv	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Р	78		
memai Resistance, Junction to Ambient (Note 6)	t < 10s	R <sub>θJA</sub>	72	°C/W	
Thermal Resistance, Junction to Case		R <sub>θJC</sub>	11.4		
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to 150	°C	

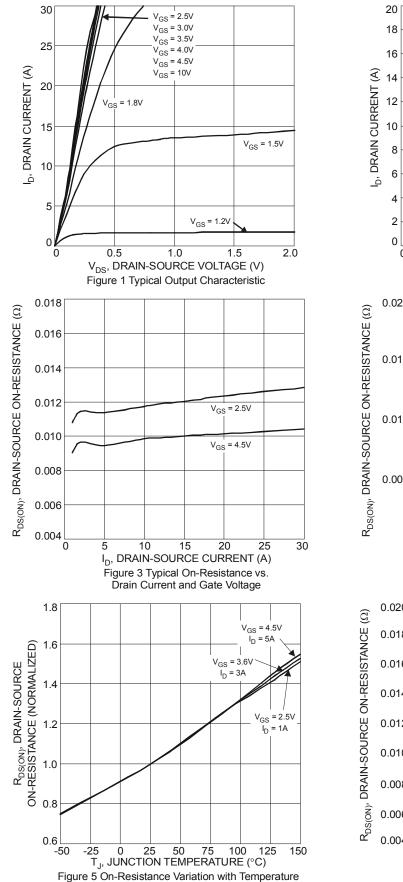
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	
Zero Gate Voltage Drain Current TJ = +25°C	I <sub>DSS</sub>	_	_	1.0	μA	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	0.71	1.1	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
			13	15.5		$V_{GS}$ = 4.5V, I <sub>D</sub> = 4.0A	
			13.5	16.5		V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 4.0A	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	—	14	19	mΩ	V <sub>GS</sub> = 3.1V, I <sub>D</sub> = 4.0A	
			15	20		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 4.0A	
			21	30		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 3.5A	
Forward Transfer Admittance	Y <sub>fs</sub>	_	25	_	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 6A	
Diode Forward Voltage	V <sub>SD</sub>	_	0.75	1.0	V	$V_{GS} = 0V, I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)						•	
Input Capacitance	Ciss		1550	_	pF		
Output Capacitance	Coss		166	_	pF	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1 0MHz	
Reverse Transfer Capacitance	Crss		145	_	pF	1 - 1.00012	
Gate Resistance	Rg	_	1.37	_	Ω	$V_{DS}$ = 0V, $V_{GS}$ = 0V, f = 1MHz	
Total Gate Charge (V <sub>GS</sub> = 2.5V)	Qg	_	8.4	_	nC		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	—	16	—	nC	V <sub>DS</sub> = 10V, I <sub>D</sub> = 6A	
Gate-Source Charge	Q <sub>qs</sub>	_	2.3	—	nC		
Gate-Drain Charge	Q <sub>gd</sub>		2.5	—	nC		
Turn-On Delay Time	t <sub>D(on)</sub>		6.9	—	ns		
Turn-On Rise Time	tr		15.5	—	ns	$V_{DD} = 10V, R_{L} = 1.7\Omega,$	
Turn-Off Delay Time	t <sub>D(off)</sub>		40.9	_	ns	$V_{GS} = 5.0V, R_G = 3\Omega$	
Turn-Off Fall Time	t <sub>f</sub>	_	12		ns		

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout
Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad
Repetitive rating, pulse width limited by junction temperature
Guaranteed by design. Not subject to product testing Notes:



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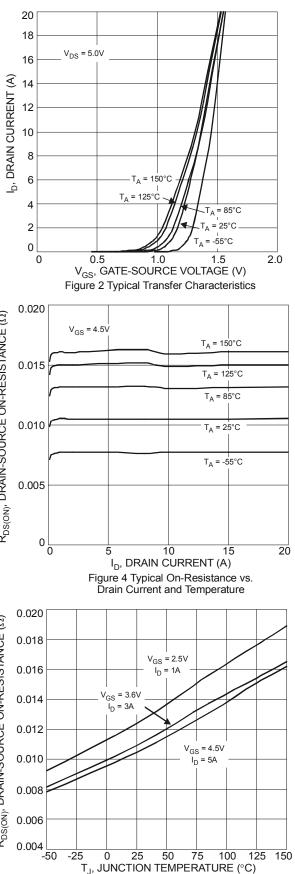
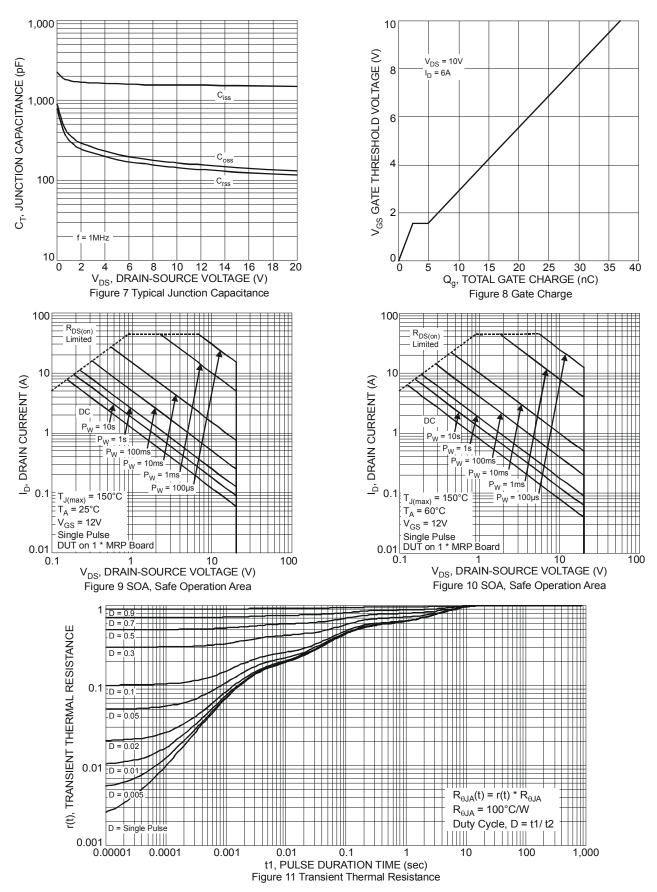


Figure 6 On-Resistance Variation with Temperature

NEW PRODUCT



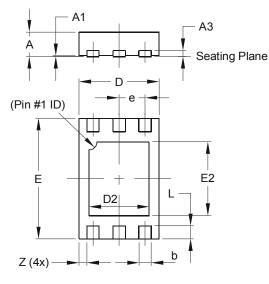
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# **Package Outline Dimensions**

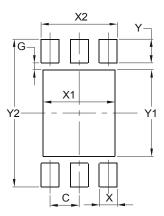
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	U-DFN2030-6 Type B					
Dim	Min Max Ty					
Α	0.55	0.65	0.60			
A1	0	0.05	0.02			
A3	-	-	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	1.40	1.60	1.50			
Е	2.95	3.05	3.00			
E2	1.74	1.94	1.84			
е	-	-	0.65			
L	0.28	0.38	0.33			
Ζ	-	-	0.20			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value		
Dimensions	(in mm)		
С	0.650		
G	0.150		
Х	0.400		
X1	1.600		
X2	1.700		
Y	0.530		
Y1	1.940		
Y2	3.300		



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